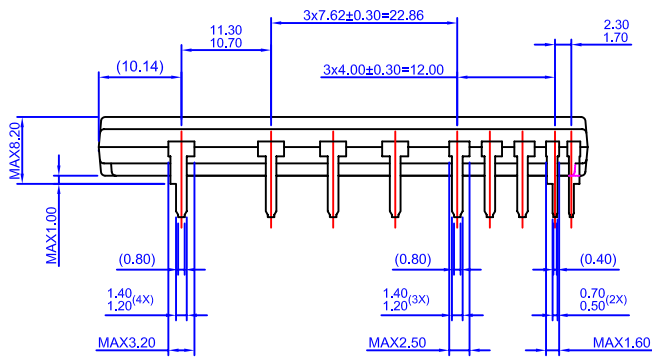
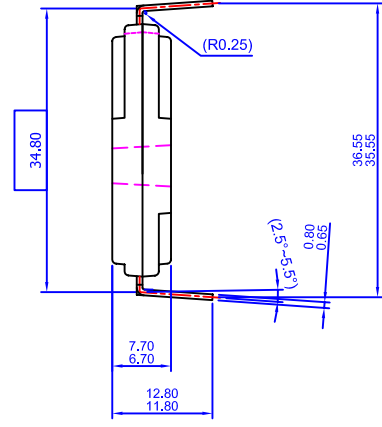
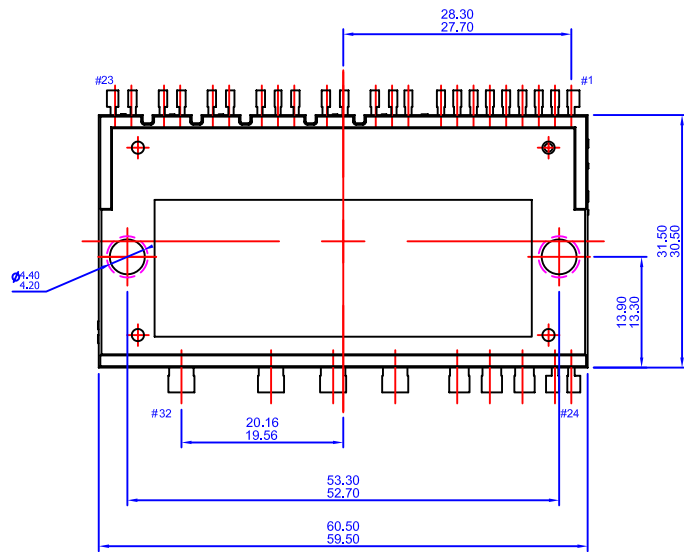
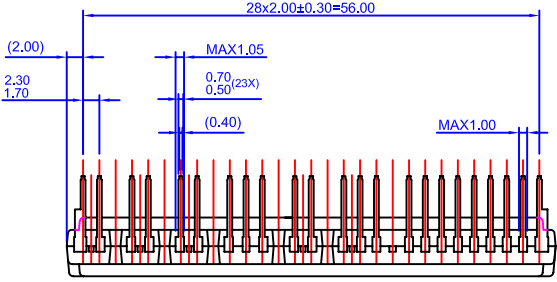


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1	RECREATED DRAWING	15 JUL 2010	KN LEE



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APPROVALS	DATE				
DRAWN: KN LEE	15 JUL 2010				
CHECKED: SW LIM					
APPROVED: JS SON					
HOWARD ALLEN		32LD, PDD STD, DBC DIP TYPE			
		SCALE	SIZE	DRAWING NUMBER	REV
		1:1	NA	MKT-MOD32BA	1
		FORMERLY: N/A	SHEET: 1 OF 1		